Solder wire GST-NP303

Product description

GENMA solder wire – the GST-NP303 solder wire is spatter-free. No contamination by flux or tin spatter on the board. Its good wetting properties allow quick soldering processes. Cleaning after soldering is not necessary.

Technical properties

	Specific value				Testing method
Diameter (mm)	0,15	0,3	0,5 / 0,6	0,8 / 1,0 / 1,2 /1,6	
Weight spindle (g)	50	250	500	1000	
Flux type	ROL1, no clean				IPC J-STD-004B
Flux content (wt%)	3,18 ± 0,30 %				IPC-TM-650 2.3.34.1
Halide content (wt%)	0,07 ± 0,03 %				IPC-TM-650 2.3.35
Insulation resistance (Ω)	> 1 x 10^{11} (40°C 90% rel. humidity)				IPC-TM-650 2.6.3.3
Insulation resistance (Ω)	> 1 x 10^{9} (85°C 85% rel. humidity)				IPC-TM-650 2.6.3.3
Migration	non				IPC-TM-650 2.6.14
Recommended solder tip temperature (°C)	350 ± 20				
Recommended storage (°C)	0 - 40				

Alloys

Name	Alloy	Melting temperature range	Advantages
NP303	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	217 - 221	Standard alloy, excellent wetting

Compliance

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU

Contains no substances more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006 (SVHC-list - dated 26.02.2024)

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